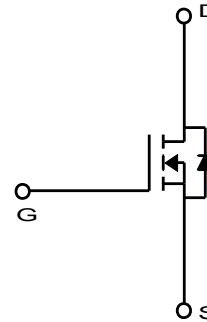


### General Description

The MDP1901 uses advanced Magnachip's MOSFET Technology, which provides high performance in on-state resistance, fast switching performance and excellent quality. MDP1901 is suitable device for DC/DC Converters and general purpose applications.

### Features

- $V_{DS} = 100V$
- $I_D = 36A$  @  $V_{GS} = 10V$
- $R_{DS(ON)} < 22m\Omega$  @  $V_{GS} = 10V$   
 $< 25m\Omega$  @  $V_{GS} = 6.0V$



### Absolute Maximum Ratings (Tc = 25°C)

| Characteristics                              | Symbol         | Rating            | Unit |   |
|--|----------------|-------------------|------|---|
| Drain-Source Voltage                         | $V_{DSS}$      | 100               | V    |   |
| Gate-Source Voltage                          | $V_{GSS}$      | ±20               | V    |   |
| Continuous Drain Current                     | $I_D$          | $T_C=25^\circ C$  | 36   | A |
|  |                | $T_C=100^\circ C$ | 24   | A |
| Pulsed Drain Current                         | $I_{DM}$       | 144               | A    |   |
| Power Dissipation                            | $P_D$          | $T_C=25^\circ C$  | 34   | W |
|  |                | $T_C=100^\circ C$ | 14   |   |
| Single Pulse Avalanche Energy <sup>(2)</sup> | $E_{AS}$       | 200               | mJ   |   |
| Junction and Storage Temperature Range       | $T_J, T_{stg}$ | -55~150           | °C   |   |

### Thermal Characteristics

| Characteristics                         | Symbol          | Rating | Unit |
|---|-----------------|--------|------|
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 65     | °C/W |
| Thermal Resistance, Junction-to-Case    | $R_{\theta JC}$ | 1.02   |      |

## Ordering Information

| Part Number | Temp. Range | Package | Packing | Rohs Status  |
|-------------|-------------|---------|---------|--------------|
| MDP1901TH   | -55~150°C   | TO-220  | Tube    | Halogen Free |

## Electrical Characteristics (Tc =25°C)

| Characteristics                                | Symbol       | Test Condition  | Min | Typ  | Max       | Unit       |
|--|--------------|---|-----|------|-----------|------------|
| <b>Static Characteristics</b>                  |              |   |     |      |           |            |
| Drain-Source Breakdown Voltage                 | $BV_{DSS}$   | $I_D = 250\mu A, V_{GS} = 0V$                               | 100 | -    | -         | V          |
| Gate Threshold Voltage                         | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\mu A$                           | 2.0 | 2.8  | 4.0       |            |
| Drain Cut-Off Current                          | $I_{DSS}$    | $V_{DS} = 80V, V_{GS} = 0V$                                 | -   | -    | 1         | $\mu A$    |
| Gate Leakage Current                           | $I_{GSS}$    | $V_{GS} = \pm 20V, V_{DS} = 0V$                             | -   | -    | $\pm 0.1$ |            |
| Drain-Source ON Resistance                     | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 35A$                                   | -   | 17   | 22        | m $\Omega$ |
|  |              | $T_J = 125^\circ C$   | -   | 28   | 33        |            |
|  |              | $V_{GS} = 6.0V, I_D = 20A$                                  |     | 19   | 25        |            |
| Forward Transconductance                       | $g_{fs}$     | $V_{DS} = 5V, I_D = 35A$                                    | -   | 35   | -         | S          |
| <b>Dynamic Characteristics</b>                 |              |   |     |      |           |            |
| Total Gate Charge                              | $Q_g$        | $V_{DS} = 50V, I_D = 20A, V_{GS} = 10V$                     | -   | 75   | 110       | nC         |
| Gate-Source Charge                             | $Q_{gs}$     |   | -   | 20   | -         |            |
| Gate-Drain Charge                              | $Q_{gd}$     |   | -   | 18   | -         |            |
| Input Capacitance                              | $C_{iss}$    | $V_{DS} = 30V, V_{GS} = 0V, f = 1.0MHz$                     | -   | 3045 | -         | pF         |
| Reverse Transfer Capacitance                   | $C_{rss}$    |   | -   | 160  | -         |            |
| Output Capacitance                             | $C_{oss}$    |   | -   | 234  | -         |            |
| Gate Resistance                                | $R_g$        | $V_{GS} = 0V, V_{DS} = 0V, F = 1MHz$                        | -   | 0.81 | -         | $\Omega$   |
| Turn-On Delay Time                             | $t_{d(on)}$  | $V_{GS} = 10V, V_{DS} = 50V, R_L = 30\Omega, R_G = 6\Omega$ | -   | 25   | 40        | ns         |
| Rise Time                                      | $t_r$        |   | -   | 12   | 20        |            |
| Turn-Off Delay Time                            | $t_{d(off)}$ |   | -   | 70   | 120       |            |
| Fall Time                                      | $t_f$        |   | -   | 20   | 35        |            |
| <b>Drain-Source Body Diode Characteristics</b> |              |   |     |      |           |            |
| Source-Drain Diode Forward Voltage             | $V_{SD}$     | $I_S = 1A, V_{GS} = 0V$                                     | -   | 0.7  | 1.2       | V          |
| Body Diode Reverse Recovery Time               | $t_{rr}$     | $I_F = 20A, di/dt = 100A/\mu s$                             | -   | 70   | 100       | ns         |
| Body Diode Reverse Recovery Charge             | $Q_{rr}$     |   | -   | 240  | -         | nC         |

Note :

1. Surface mounted RF4 board with 2oz. Copper.
2. Starting  $T_J = 25^\circ C, L = 1mH, I_{AS} = 20A, V_{DD} = 50V, V_{GS} = 10V$

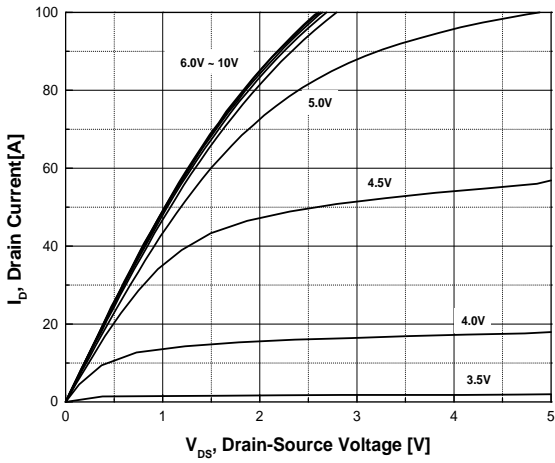


Fig.1 On-Region Characteristics

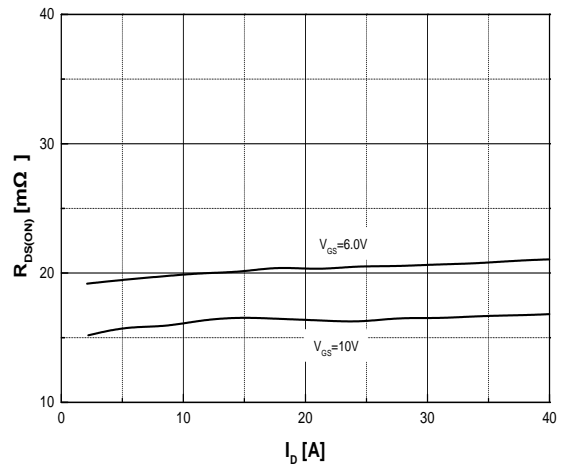


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

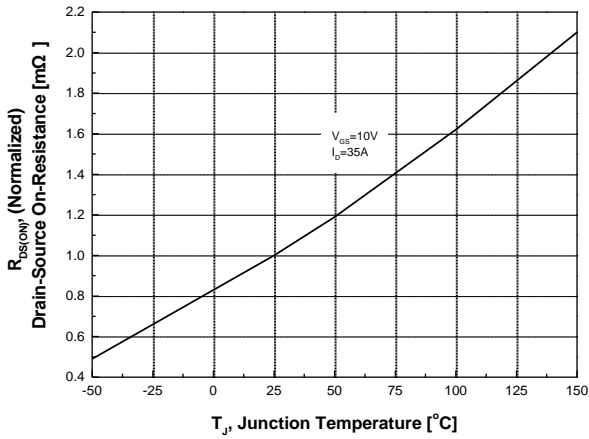


Fig.3 On-Resistance Variation with Temperature

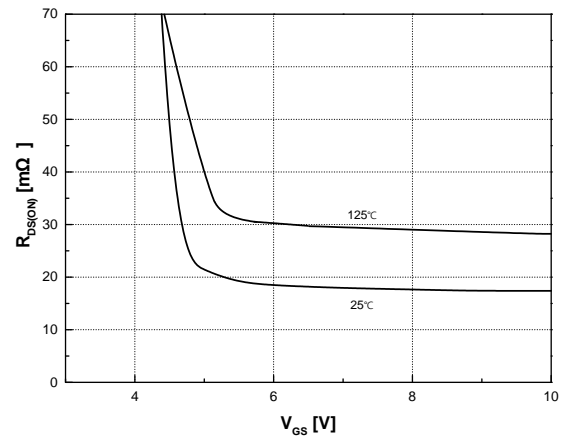


Fig.4 On-Resistance Variation with Gate to Source Voltage

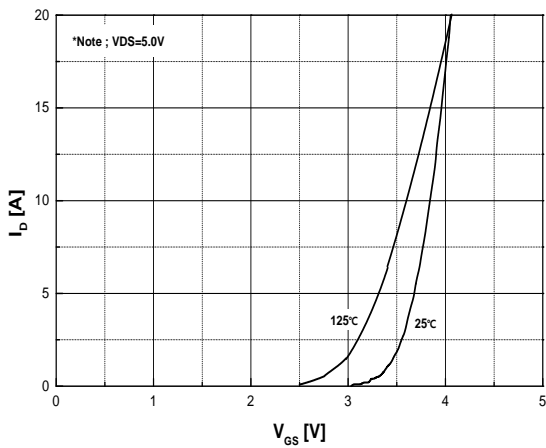


Fig.5 Transfer Characteristics

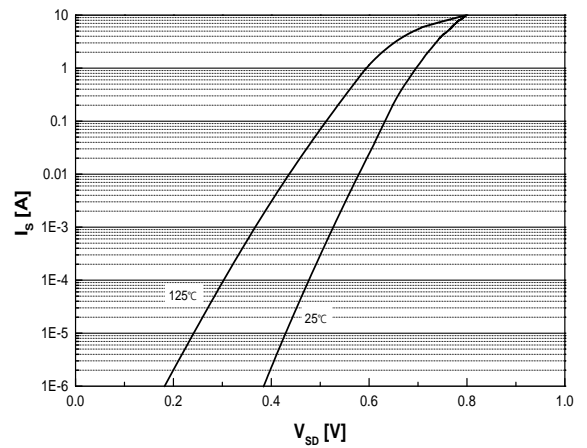
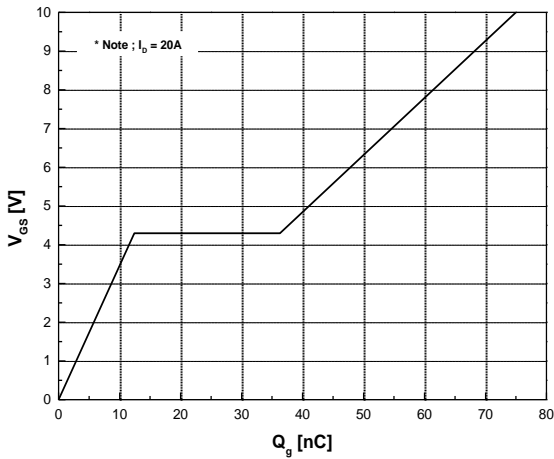
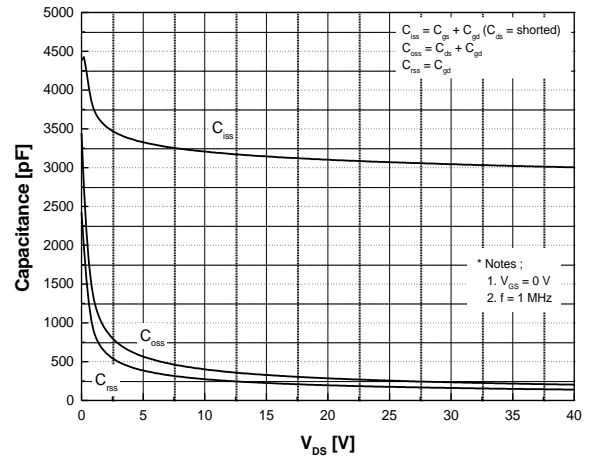


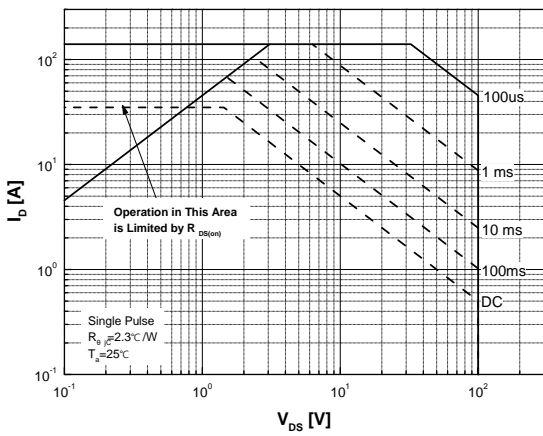
Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature



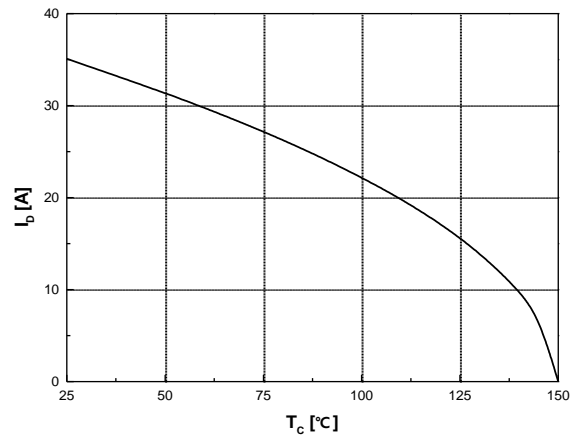
**Fig.7 Gate Charge Characteristics**



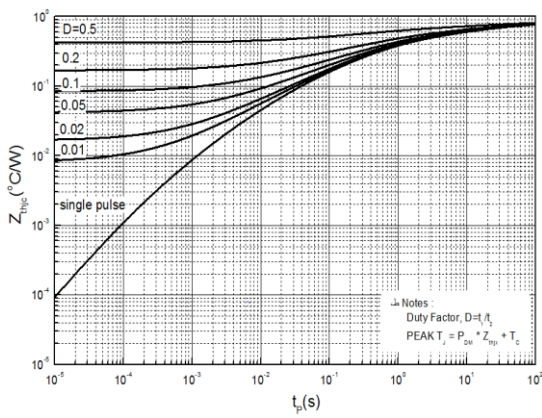
**Fig.8 Capacitance Characteristics**



**Fig.9 Maximum Safe Operating Area**



**Fig.10 Maximum Drain Current vs. Case Temperature**

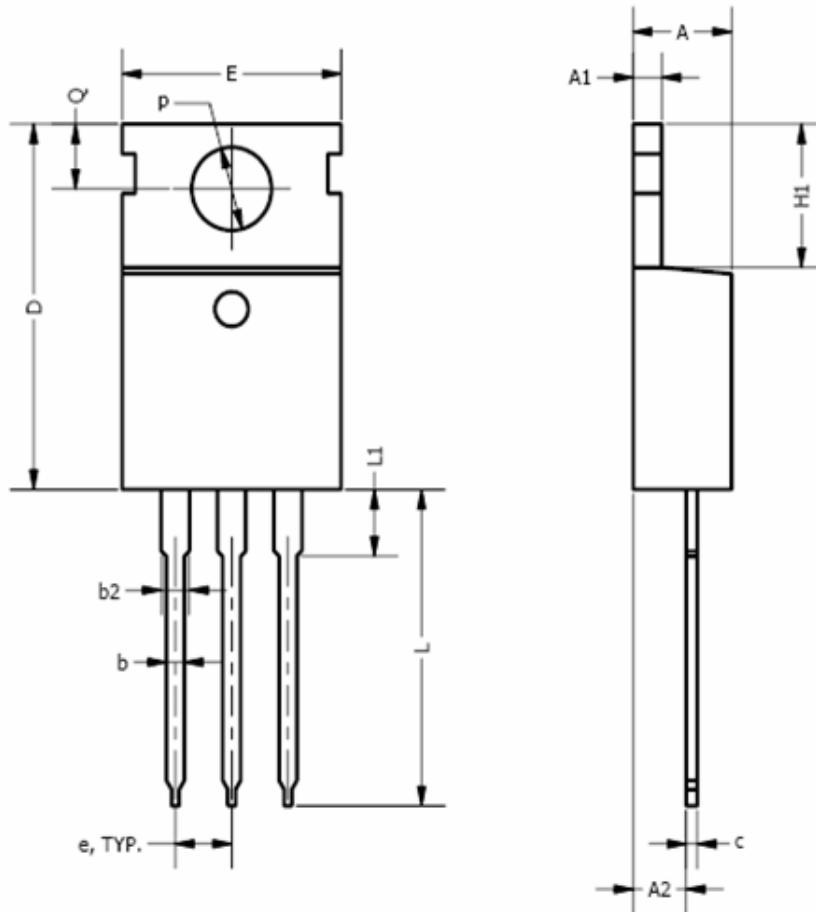


**Fig.11 Transient Thermal Response Curve**

**Physical Dimensions**

**TO-220**

Dimensions are in millimeters unless otherwise specified




| Symbol   | Min      | Nom  | Max   |
|----------|----------|------|-------|
| A        | 3.56     |      | 4.83  |
| A1       | 0.50     |      | 1.40  |
| A2       | 2.03     |      | 2.92  |
| b        | 0.38     | 0.69 | 1.02  |
| b2       | 1.14     | 1.45 | 1.78  |
| c        | 0.36     |      | 0.61  |
| D        | 14.22    |      | 16.51 |
| e        | 2.54 TYP |      |       |
| E        | 9.65     |      | 10.67 |
| H1       | 5.84     |      | 6.86  |
| L        | 12.70    |      | 14.73 |
| L1       |          |      | 6.35  |
| $\phi P$ | 3.53     |      | 4.09  |
| Q        | 2.54     |      | 3.43  |

Note : Package body size, length and width do not include mold flash, protrusions and gate burrs.

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